

PEDESTAL CLOSURES

MOISTURE PLUGS AT CABLE ENDS

CONTENTS	PAGE
1. GENERAL	1
2. DESCRIPTION—8962 MULTIMOLD	1
3. INSTALLATION	3
4. B ENCAPSULANT	8

1.03 At existing pedestal closure locations, where moisture has entered the cable, moisture plugs should not be placed until the moisture has been purged from the cable. (Section 629-295-301 outlines the method of removing moisture from the cable.) After the moisture has been removed from the cable, moisture plugs should be placed in each pedestal closure.



1. GENERAL

1.01 This section covers the method of placing moisture plugs in cable sheath openings at new or existing above ground pedestal-type closure locations to prevent the entrance of moisture into the cable core.

1.02 Moisture plugs should be placed in all new or existing cables subject to high water or flooding as called for on the work print.

Note: Filled core cables do not require moisture plugs.

2. DESCRIPTION—8962 MULTIMOLD

2.01 The 8962 Multimold (Fig. 1) consists of the following:

- (a) A flat piece of clear plastic with a mesh material bonded to one side
- (b) A pressure sensitive adhesive on each end
- (c) A strip of sealing tape bonded to the bottom.

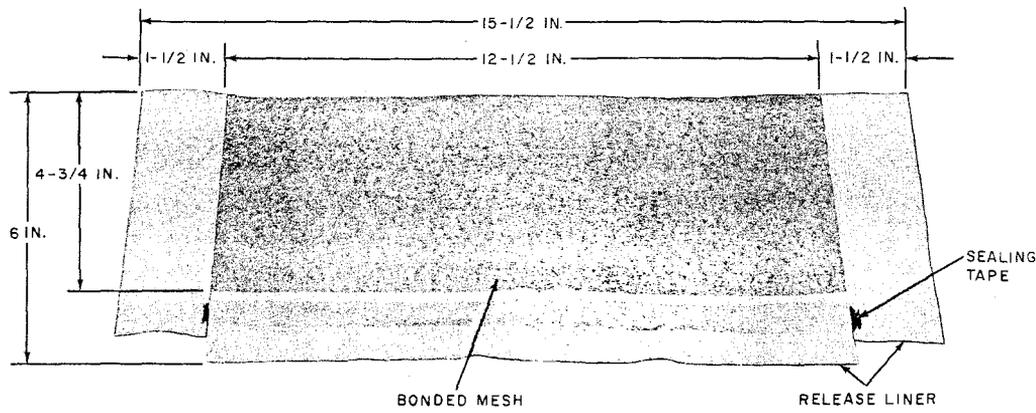


Fig. 1—8962 Multimold

**Reprinted to comply with modified final judgment.

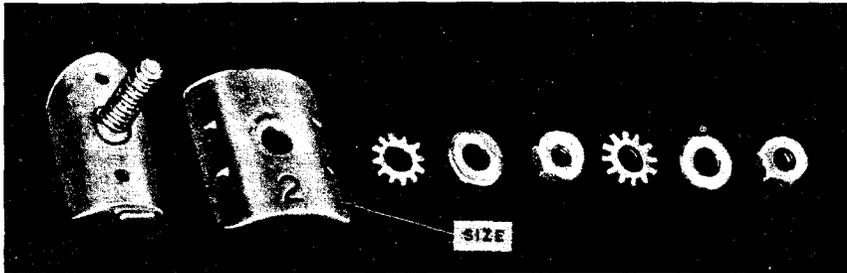
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2.02 Parts associated with the 8962 Multimold, which must be ordered separately, are as follows:

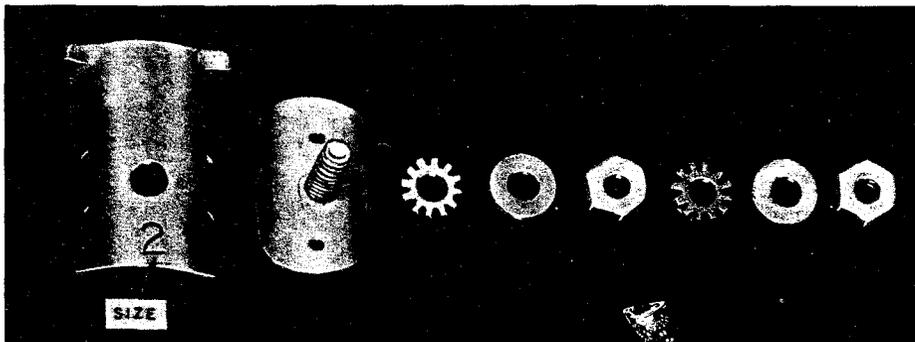
(a) *B or C Bond Clamp (Fig. 2)*—Used in conjunction with the strap to bond the metallic shield of the cable to the ground bracket of the closure. Select the correct bond clamp size required, as listed in Table A.

TABLE A
B OR C BOND CLAMP

CABLE DIAMETER (INS.)	SIZE
Up to 0.8	1
Over 0.8 to 1.6	2
Over 1.6	3



B BOND CLAMP



C BOND CLAMP

Fig. 2—B and C Bond Clamp

- (b) **Strap, No. 6 Stranded Copper Wire** (Fig. 3)—Used to provide positive continuity between the bond clamp and the closure ground bracket.

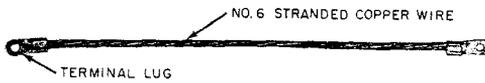


Fig. 3—Strap, C Bond Clamp (11 Inch)

- (c) **B Encapsulant** (Fig. 4)—A nonexpanding polyurethane compound enclosed in a two-part plastic bag. It is available in two sizes:

- 180 grams—approximately 6 oz.
- 300 grams—approximately 10 oz.



Fig. 4—B Encapsulant

3. INSTALLATION

SINGLE SHEATH CABLE

3.01 At all new pedestal closure locations, where moisture plugs are required, place the plug in single sheath cables, as follows:

- (a) Mark and score the sheath or sheaths 1 inch below the bottom of the ground bracket.
- (b) With a carding brush, scuff the sheath for approximately 4 inches below the score mark.
- (c) Remove the sheath from between the score marks. **Do not remove** the core wrapper until after the bond clamp has been placed.
- (d) Place the B or C Bond Clamp and Strap as illustrated in Fig. 5.
- (e) Remove the core wrapper from the cable.

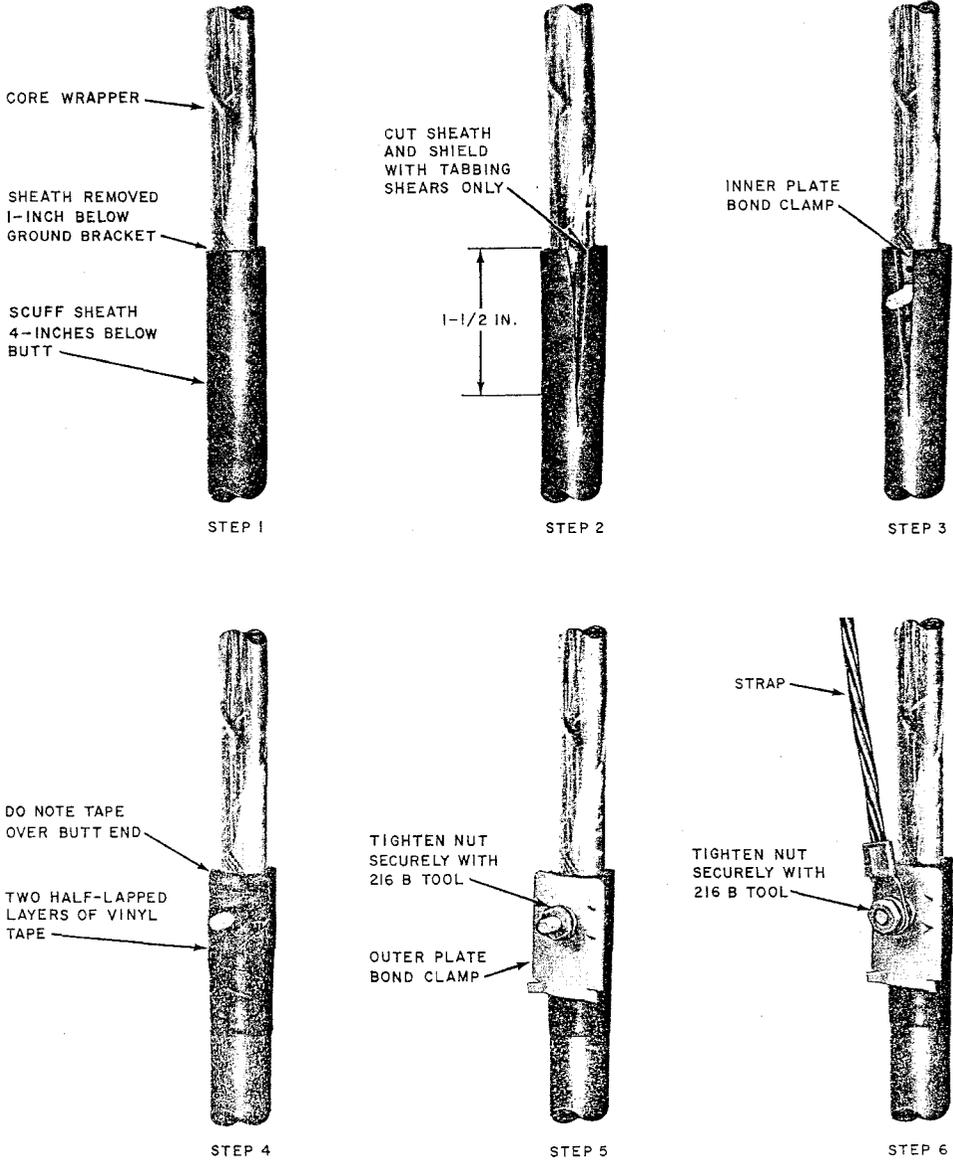


Fig. 5—Bond Clamp and Strap Placed

- (f) As each unit binder is removed, approximately 3 inches above the butts, place Binder Group Identification Ties around each binder group (Fig. 6).

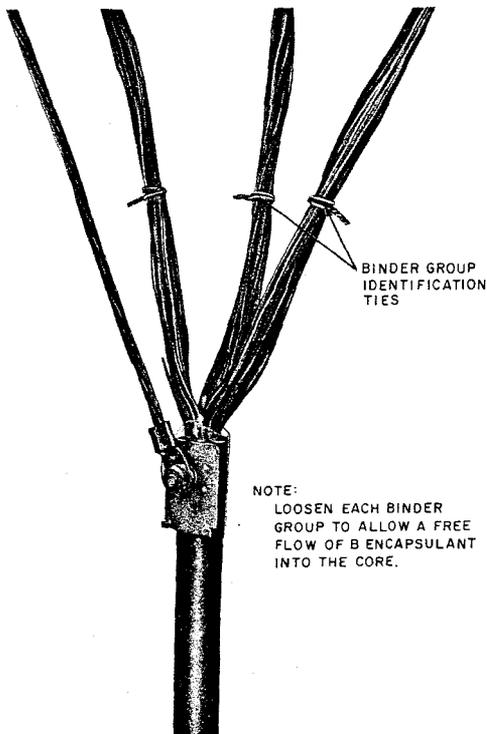


Fig. 6—Binder Group Identification Ties Placed

Note: As the Binder Group Identification Ties are placed, loosen each binder group to allow a free flow of B Encapsulant into the core of the cable.

- (g) To obtain the proper length mold, form the Multimold snugly around the ground clamp and circumference of the cable. Mark the surface of the Multimold where the end of the adhesive overlap overlaps the Multimold. The bonded mesh should be adjacent to the inner edge of the adhesive overlap (Fig. 7).

- (h) Remove the Multimold from around the cable. Cut the Multimold at the adhesive overlap mark (Fig. 8).

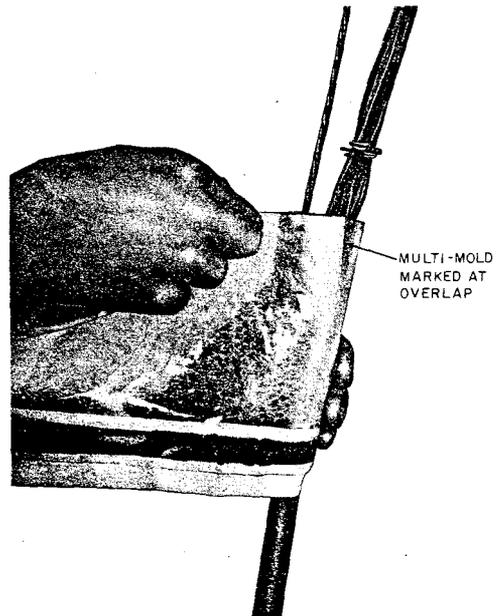


Fig. 7—Marking Multimold

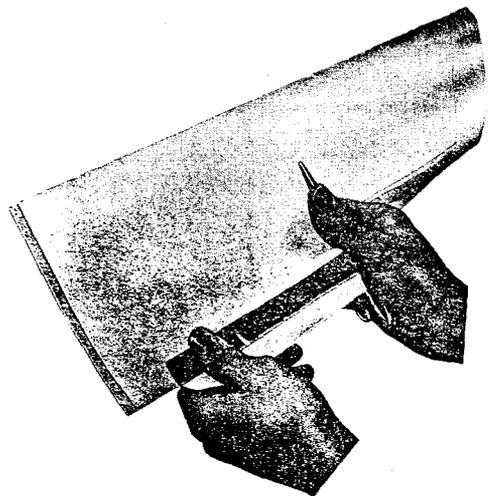


Fig. 8—Cutting Multimold

- (i) Remove the release liners from the adhesive overlap and sealing tape (Fig. 9).

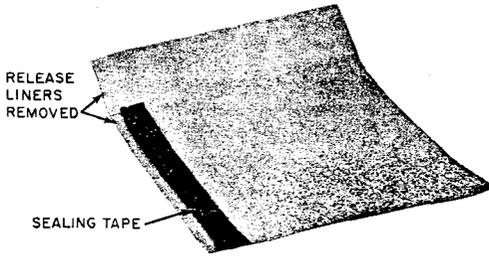


Fig. 9—Release Liners Removed

- (j) Place the mold on the cable so:

- It will extend a minimum of 1-1/2 inches and not to exceed 2 inches above the sheath opening.
- The sealing tape is below the bond clamp slit.
- The stud in the bond clamp will be opposite the overlap.

- (k) Wrap the mold snugly around the circumference of the cable. Being careful not to form wrinkles, seal the mold at the adhesive overlap. To seal the bottom of the mold, squeeze the sealing tape firmly (Fig. 10).

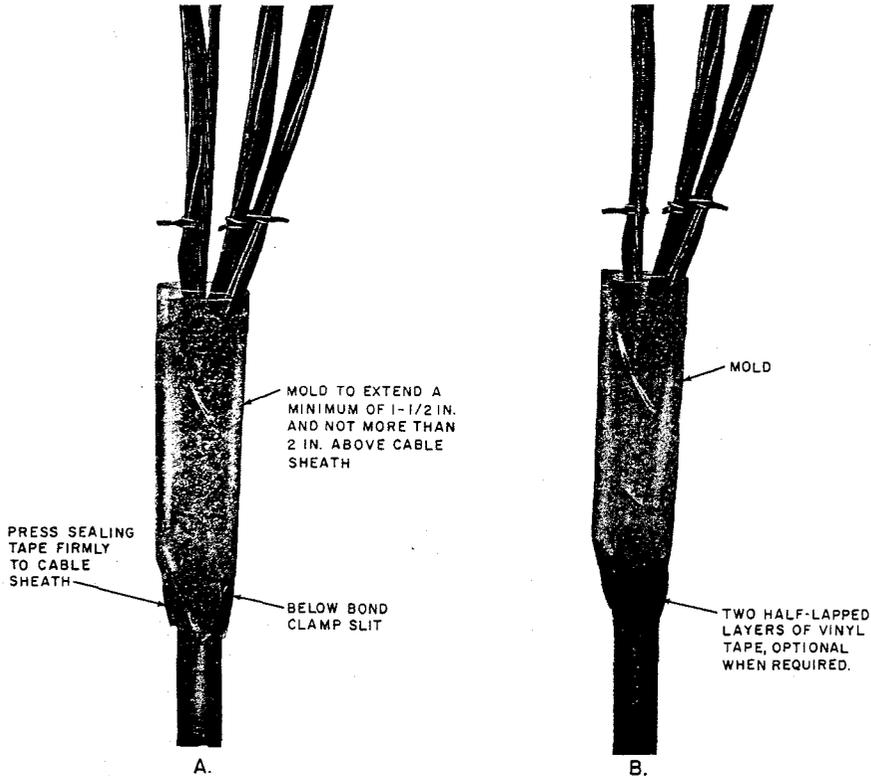


Fig. 10—Mold in Place

Note: To ensure a tight seal, where the bottom of the mold joins the cable, place two half-lapped layers of vinyl tape around the joint.

- (l) Form the strap and bond to the ground bracket by means of 10—32 machine screw, nut and washers (lock and flat) (Fig. 11).

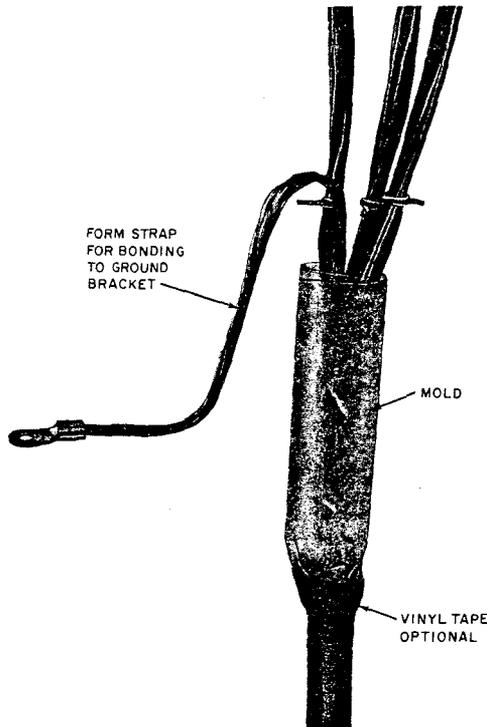


Fig. 11—Bonding Strap Formed

Note: All straps in the closure should be bonded to the ground bracket at one central location.

- (m) Where mechanical support is required, place WE-1 Cable Ties around the cable and secure to the ground bracket. Do not place cable ties around the mold until the B Encapsulant has set.
- (n) Prepare and fill the mold as outlined in Part 4.

DUAL SHEATH CABLES

3.02 At all new pedestal closure locations, where moisture plugs are required, place the plug in dual sheath cables as follows:

- (a) Mark and score the outer sheath 1 inch below the bottom of the ground bracket.
- (b) With a carding brush, scuff the outer sheath approximately 4 inches below the score mark.
- (c) Remove the outer sheath from the cable. Score the inner sheath 1/2-inch from the butt of the outer sheath. Remove the inner sheath (Fig. 12).
- (d) Place the B or C Bond Clamp and Strap as illustrated in Fig. 5.
- (e) Place the mold on the cable as outlined in 3.01, (e) through (m). Prepare and pour the B Encapsulant as outlined in Part 4.

3.03 At all existing pedestal closure locations, where moisture plugs are required (see 1.03), and the existing tabs can be reused, place the plug as follows:

Note: Where existing tabs cannot be reused, place the bond clamp as illustrated in Fig. 5. Section 631-600-301 covers the replacement of bonds in existing cables.

- (a) Remove the sealing clamp.
- (b) Remove the tape from around the inner sheath clamp.
- (c) Remove the inner sheath clamp being careful not to damage the cable shields.
- (d) Examine the conductors for opens, shorts, crosses, grounds, and shiners on each side of the area where the inner sheath clamps were located. Repair all troubles or faults.
- (e) Verify that the cable shield is not broken and continuity can be maintained with the bond clamp.
- (f) Move or replace the Binder Group Identification Ties so they are a minimum of 3 inches above the cable butt.

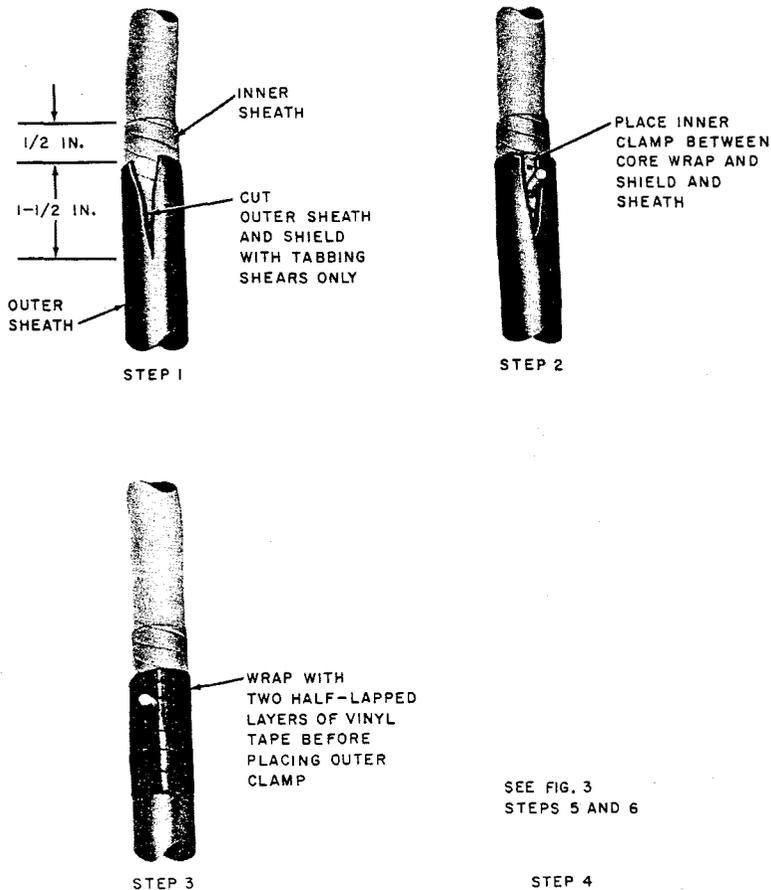


Fig. 12—Dual Sheath Preparation for Bond Clamp

(g) Figure 13 illustrates the bond clamp being installed.

(h) Place the mold on the cable as outlined in 3.01, (e) through (m). Prepare and pour the B Encapsulant as outlined in Part 4.

4. B ENCAPSULANT

PRECAUTIONS

4.01 Before handling B Encapsulant observe the following precautions:

- (a) Protect hands with gloves or with Kerodex 71 and Kerodex 55[®] in accordance with instructions on the containers.
- (b) Avoid contact with skin and breathing of vapors while pouring the mixed compounds.
- (c) Use in well ventilated areas.
- (d) In case of accidental contact with eyes, flush with clear water for 15 minutes and get medical attention.

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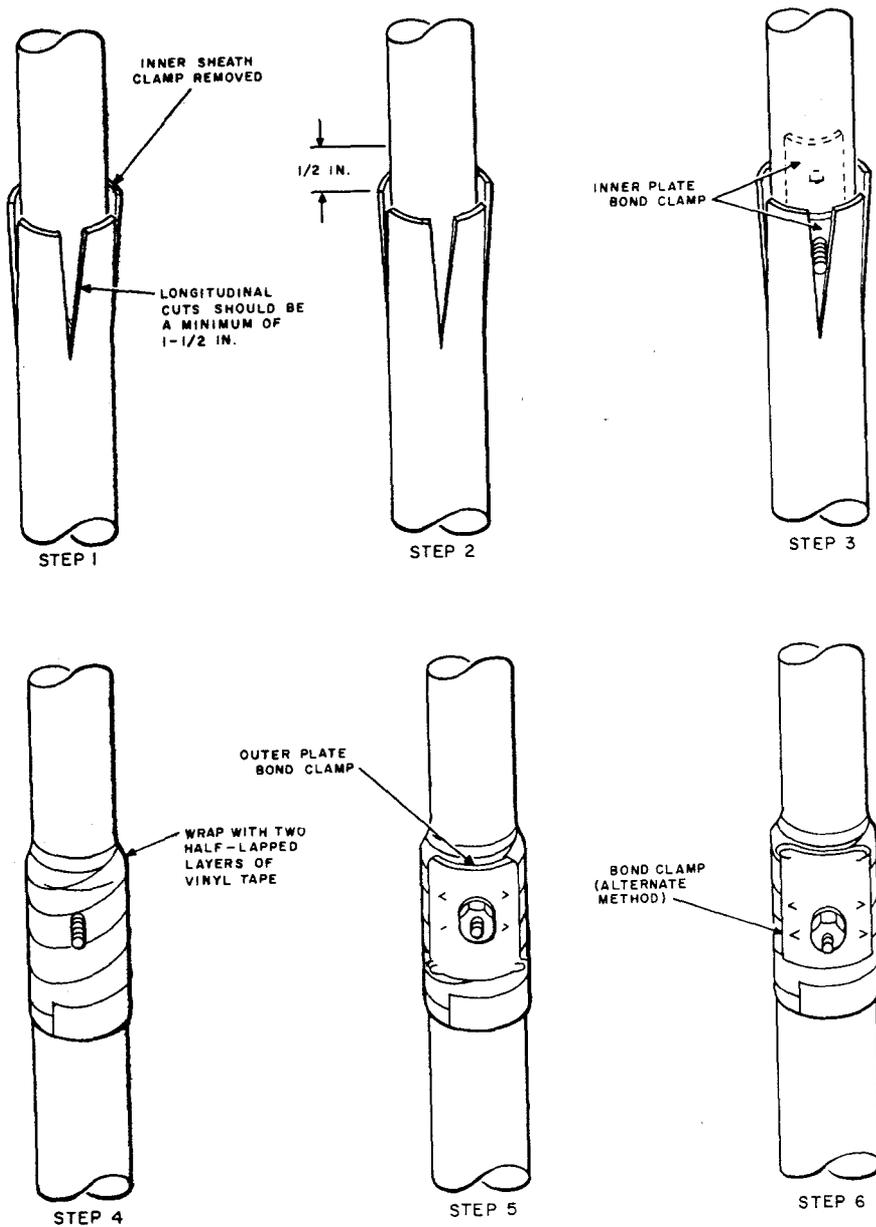


Fig. 13—Installing Bond Clamp—Existing Closure

SECTION 631-600-305

4.02 Prepare the B Encapsulant and pour into the mold as follows:

Note: Do not remove the B Encapsulant from the containers until ready to use.

- (1) Remove the B Encapsulant from the containers.
- (2) Break the dividing seal separating the two components.
- (3) Mix the two components, in the plastic bag, by kneading thoroughly. During the mixing process scrape the compound from the edges and corners of the bag.

(4) When the B Encapsulant is uniform in color (dark green), with no streaking, it is ready to pour into the mold.

(5) Cut a diagonal opening across one corner of the plastic bag to form a pouring lip.

(6) Pour the B Encapsulant into the mold. The mold should be filled to the top. Where necessary, top-off the mold with additional encapsulant.

(7) Do not disturb the moisture plug until the compound has cured.